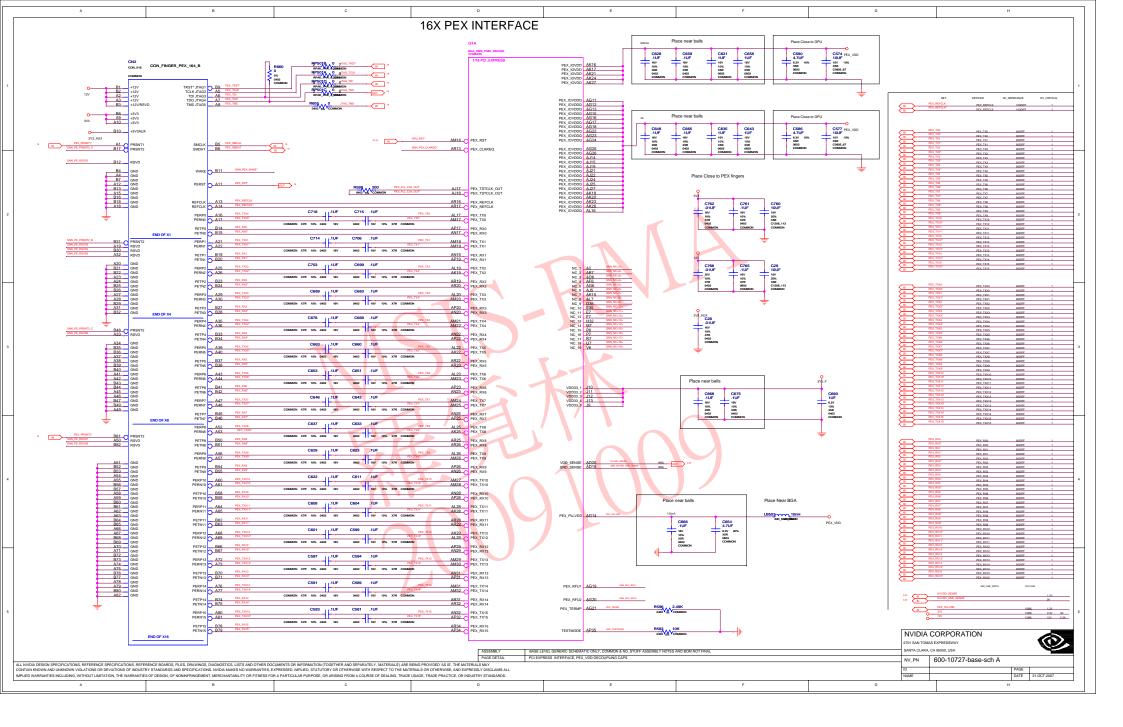
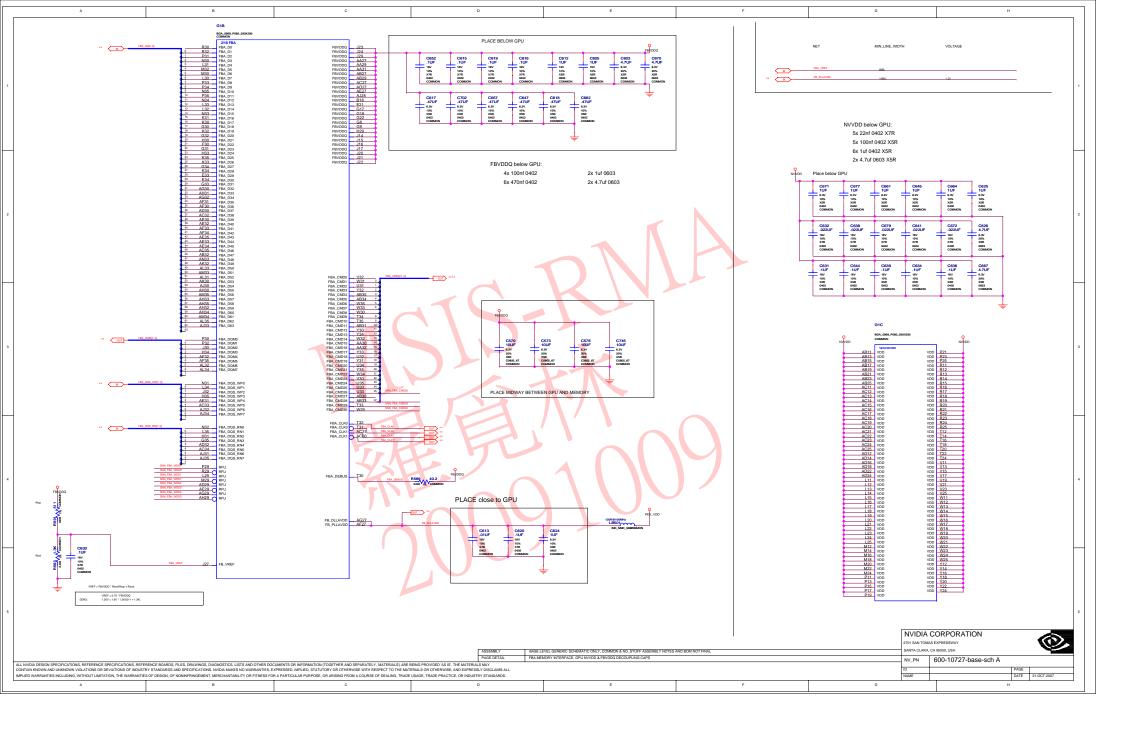
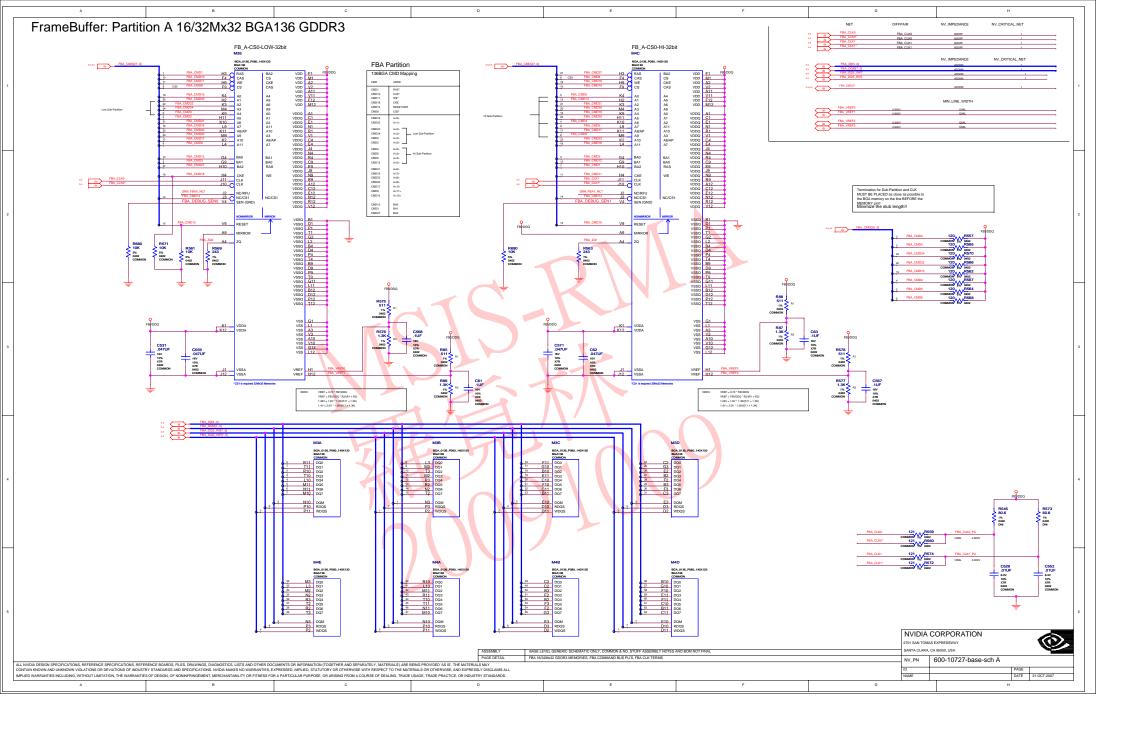
P727-A01: G96, GB1-128, GDDR3, DL-DVI, DL-DVI/VGA, SD/HDTV V129-122 PAGE SUMMARY: Page 1: TABLE OF CONTENTS **REV 1.2 HISTORY** Page 2: PCI EXPRESS INTERFACE, PEX_VDD DECOUPLING CAPS Page 3: FBA MEMORY INTERFACE, GPU NVVDD & FBVDDQ DECOUPLING CAPS 04/01 Page 4: FBA 16/32Mx32 GDDR3 MEMORIES, FBA COMMAND BUS PU'S, FBA CLK TERMS PAGE 12.Remove J1 Slim-DSUB connector Page 5: FBA MEMORY FBVDDQ DECOUPLING CAPS Page 6: FBA 16/32Mx32 GDDR3 A1 MEMORIES, FBA COMMAND BUS PU'S, FBA CLK TERMS PAGE 15.Add R761 and R762 to reserve pull down DP AUX Page 7: FBC MEMORY INTERFACE Change F503 and F504 footprint to 1812 size Page 8: FBC 16/32MX32 GDDR3 MEMORIES, FBC CMD BUS PU'S, FBC CLK TERMS Remove DP J8 Pin25, Pin26 Page 9: FBC MEMORY FBVDDQ DECOUPLING CAPS, GPU GND CONNECTIONS PAGE 18.Change U514~U517 to EM1~EM6 Page 10: FBC 16/32MX32 GDDR3 C1 MEMORIES, FBC CMD BUS PU'S, FBC CLK TERMS Page 11: DACA FILTERS, DACA SYNC BUFFERS & DB15 SOUTH PAGE 19.Add 2pin Fan control circuit Page 12: DACC FILTERS, DACC SYNC BUFFERS & DB15 MID Page 13: TMDS LINK A/B, DVI CONNECTOR SOUTH PAGE 23.Add C120,C149 10uF 1206 footprint to reserve PEX_VDD power Page 14: TMDS LINK C/D, AC COUPLING, HDMI Page 15: TMDS LINK E/F, AC COUPLING, DP 04/08 Page 16: MIOA & MIOB, SLI CONNECTOR Page 17: DACB FILTERS, MINIDIN CONNECTOR NORTH, SD/HD VIDEO OUTPUT CONNECTOR PAGE 22. Add R92 0805 0ohm Resistor for 3V3 bypass to 2V5 power Page 18: SPDIF-IN, XTAL, MECHANICALS, THERMALS Page 19: EXTERNAL THERMAL SENSOR, 4PIN FAN CONTROL, GPIO **REV 1.21 HISTORY** Page 20: BIOS ROM, HDCP ROM, STRAPPING OPTIONS Page 21: HYBRID POWER CIRCUIT 06/04 Page 22: POWER SUPPLY LINEARS: 5V, DDC5V, IFP PLLVDD, IFP IOVDD, MIO VDD, 3V3 FILTER, 12V FILTER PAGE 20.Add R774 10K pull down resistor for HDA issue Page 23: POWER SUPPLY: FBVDDQ +PEX_VDD SINGLE PHASE SWITCHER Page 24: POWER SUPPLY: NVVDD DUAL PHASE SWITCHER REV 1.22 HISTORY Page 25: POWER SUPPLY: Dynamic NVVDD PAGE 22. Reverse Diode at 5V regulator input side to prevent Leakage to 12V PAGE 22. Reverse CAP SOLID for A2V5 NVIDIA CORPORATION ANTA CLARA CA 95050 LISA 600-10727-base-sch A ALL LIVINIA DESIGNI SPECIFICATIONS, REFFERENCE SPECIFICATIONS, REFFERENCE BOARDS, FLES, DRAWNINSS, DIAMONSTICS, LISTS AND CINEER DOCUMENTS OR REFORMATION PROSENTER AND SEPHARIETY, VARTERIALS) ARE BEING PROVIDED AS IS. THE MITTERIALS MAY CONTINUE WAS AND THE CONTINUE AND THE PROVIDED AS IS. THE MITTERIALS MAY CONTINUE AND THE PROVIDED AS IS. THE MITTERIALS MAY CONTINUE AND THE PROVIDED AS IS. THE MITTERIALS MAY CONTINUE AND THE PROVIDED AS IS. THE MITTERIALS MAY CONTINUE AND THE PROVIDED AS IS. THE MITTERIAL SHAPE AND THE

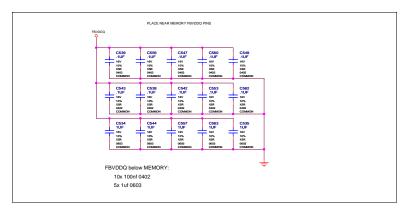




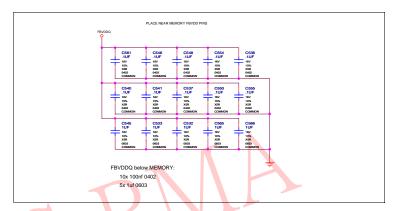


FRAME BUFFER: PARTITION A DECOUPLING

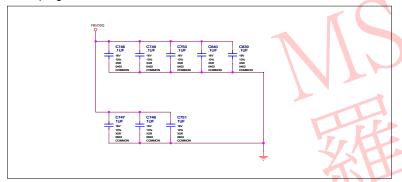
Decoupling for FBA 0..31



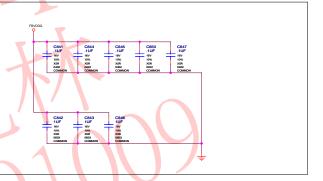
Decoupling for FBA 32..63



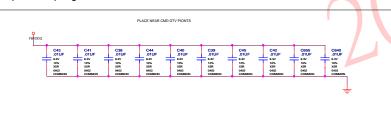
Decoupling for FBA A1 0..31



Decoupling for FBA A1 0..31



Return path coupling GND/FBVDDQ for FBA



		NVIDIA CORPORATION	
			IS EXPRESSWAY
EMBLY	DIGE LEVEL GENERAL GOVERNATIO CHEET, COMMON & NO. STATE TO TEST AND DOWN NOT THOSE	SANTA CLARA, CA 95050, USA	
E DETAIL	FBA MEMORY FBVDDQ DECOUPLING CAPS	NV_PN	600-10727-base-sch A

ALL NUOLA DESIGN SPECIFICATIONS, REFERENCE BROADS, FLES, DRAWINGS, DIAGNOSTICS, LISTS AND OTHER DCLIMENTS OR PRFORMATION (TOGETHER AND SEPARATELY, MATERIALS) ARE BEING PROVIDED AS IS: THE MATERIALS MY CONTINUING UNACITORS OR REVENTED TO THE MATERIALS OF CHERKING. MICH MATERIAL SOFT TO THE MATERIALS OF THE MATERIAL SOFT TO THE MATERIAL SOFT TO

